

SUBMINIATURE SOLID STATE LAMP

Part Number: AM27MGC08

Mega Green

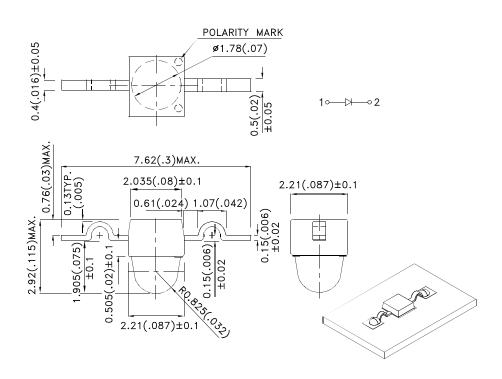
Features

- Subminiature package.
- Yoke lead.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Mega Green source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.





SPEC NO: DSAC5140 **REV NO: V.5** DATE: MAY/18/2009 PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Ting.Li ERP: 1202000979

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
AM27MGC08	Mega Green (AlGaInP)	WATER CLEAR	280	600	20°

Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	IF=20mA
λD [1]	Dominant Wavelength	Mega Green	570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Mega Green	26		nm	IF=20mA
С	Capacitance	Mega Green	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Mega Green	2.1	2.5	V	I=20mA
lR	Reverse Current	Mega Green		10	uA	V _R =5V

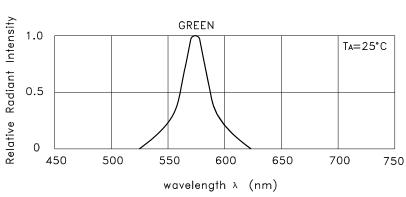
- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter Mega Green		Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

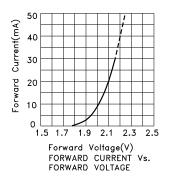
SPEC NO: DSAC5140 **REV NO: V.5** DATE: MAY/18/2009 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Ting.Li ERP: 1202000979

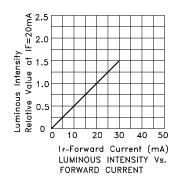


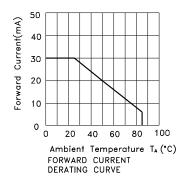
RELATIVE INTENSITY Vs. WAVELENGTH

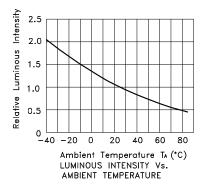
Mega Green

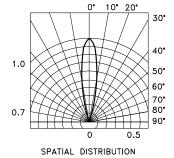
AM27MGC08











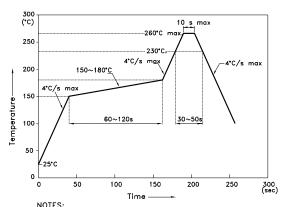
 SPEC NO: DSAC5140
 REV NO: V.5
 DATE: MAY/18/2009
 PAGE: 3 OF 5

 APPROVED: WYNEC
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AM27MGC08

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



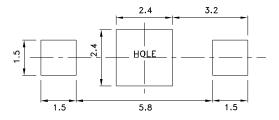
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

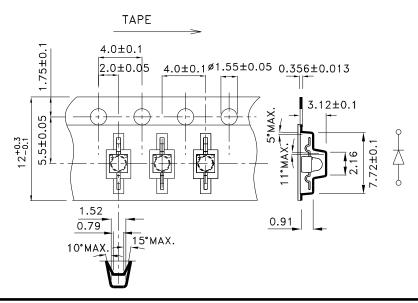
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

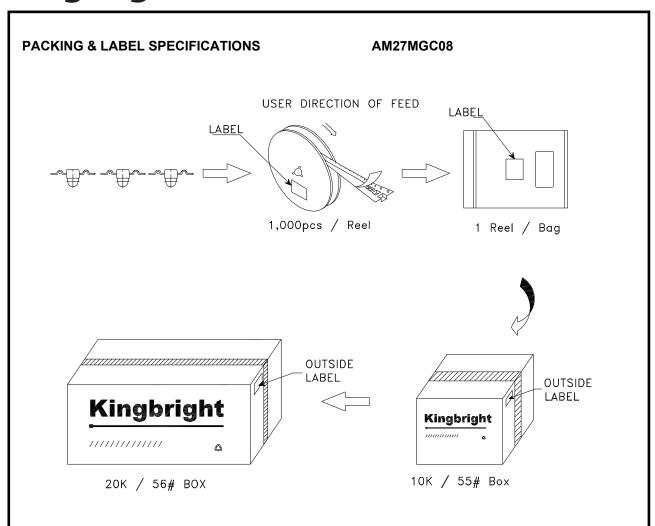
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

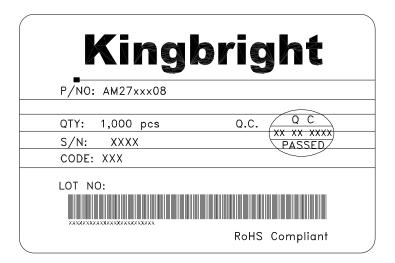


Tape Dimensions (Units: mm)



SPEC NO: DSAC5140 **REV NO: V.5 DATE: MAY/18/2009** PAGE: 4 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Ting.Li ERP: 1202000979





SPEC NO: DSAC5140 APPROVED: WYNEC REV NO: V.5 CHECKED: Allen Liu DATE: MAY/18/2009 DRAWN: Ting.Li PAGE: 5 OF 5 ERP: 1202000979